URL for Additional Information

 PART INFORMATION

 Mfg Item Number
 SGTL5000XNLA3R2

 Mfg Item Name
 QFN-EP 20 3*3*0.55P0.4

SUPPLIER Company Name Freescale Semiconductor Inc Company Unique ID 14-141-7928 Response Date 2012-03-13 Response Document ID 6243K50001S002A1.3 Contact Name Freescale Semiconductor Inc Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response** Representative Phone 512-895-3406 Representative Email eppanlst@freescale.com

DECLARATION

EU RoHS
Pb Free
Yes
HalogenFree
Plating Indicator
EU ROHS Exemption(s)

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MANUFACTURING Mfg Item Number SGTL5000XNLA3R2 QFN-EP 20 3*3*0.55P0.4 Mfg Item Name Version ALL Weight 0.015800 UoM Unit Volume EACH J-STD-020 MSL Rating 3 Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles 3

2002/95/EC **RoHS Directive** RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium **RoHS Definition** Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium

Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies for issues that arise regarding information the Supplier **RoHS Legal Definition** Sale applicable to such part(s) shall apply. **RoHS Declaration** 1 - Item(s) do not contain RoHS restricted substances per the definition above Accepted Supplier Acceptance Signature **Daniel Binyon** Exemptions in this part List of Freescale Accepted Exemptions 6(a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c): Copper alloy containing up to 4% lead by weight 7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV: Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors

15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart	SubPart%	REACHPPM	REACH%
Local France Platform	0.0001							PPM			
Lead Frame Plating	0.0001					_	g			_	_
Lead Frame Plating		Metals	Lead, metallic lead and lead alloys	7439-92-1		0	g	200	0.02	0	0
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.0001	g	999800	99.98	6329	0.6329
Die Encapsulant	0.0067						g				
lie Encapsulant		Plastics/polymers	4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl digycidyl ether	85954-11-6		0.000644	g	96187	9.6187	40759	4.0759
ie Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.000012	g	1804	0.1804	759	0.0759
ie Encapsulant		Glass	Silica, vitreous	60676-86-0		0.006044	g	902009	90.2009	382534	38.2534
Bonding Wire	0.0002						g				
onding Wire		Metals	Gold, metal	7440-57-5		0.0002	g	1000000	100	12658	1.2658
ilicon Semiconductor Die	0.0006						g				
licon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000012	g	20000	2	759	0.0759
ilicon Semiconductor Die		Glass	Silicon, doped	-		0.000588	g	980000	98	37215	3.7215
opper Lead Frame	0.0081						g				
opper Lead Frame		Metals	Copper, metal	7440-50-8		0.007809	g	963955	96.3955	494245	49.4245
opper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.000007	g	825	0.0825	443	0.0443
opper Lead Frame		Metals	Iron, metal	7439-89-6		0.00019	g	23500	2.35	12025	1.2025
copper Lead Frame		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.000001	g	170	0.017	63	0.0063
copper Lead Frame		Metals	Silver, metal	7440-22-4		0.000081	g	10000	1	5126	0.5126
opper Lead Frame		Metals	Tin, metal	7440-31-5		0.000002	g	300	0.03	126	0.0126
opper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00001	g	1250	0.125	632	0.0632
Ion-Conductive Epoxy/Adhesive	0.0001						g				
Ion-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Other halogenated organic compounds	-		0	g	900	0.09	0	0
on-Conductive Epoxy/Adhesive		Plastics/polymers	Other phenolic resins	-		0.000005	g	50020	5.002	316	0.0316
on-Conductive Epoxy/Adhesive		Plastics/polymers	Plastic: SI - Silicone Rubber	-		0.00003	g	300120	30.012	1898	0.1898
on-Conductive Epoxy/Adhesive		Glass	Dimethyl silicone polymer with silica	67762-90-7		0.00006	g	600241	60.0241	3797	0.3797
Ion-Conductive Epoxy/Adhesive		Plastics/polymers	Other acrylic/epoxy resin mixture			0.000005	q	48719	4.8719	316	0.0316

LINKS

MCD LINK

http://www.freescale.com Freescale website

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

RoHS signed letter China RoHS http://www.freescale.com/chinarohs

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf ELV signed letter

http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf Conflict Minerals statement FREESCALE ENVIRONMENTAL INFORMATION

EPP website

http://www.freescale.com/epp

FAQ

Technical Service Request

LINKS TO BLANK IPC1752 FORMS

http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

Blank IPC1752 v0.9 Form $http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf$ http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf Blank IPC1752 v1.1 Form

IPC1752 XML LINKS

http://www.freescale.com/mcds/SGTL5000XNLA3R2_IPC1752_v09.xml

http://www.freescale.com/mcds/SGTL5000XNLA3R2_IPC1752_v11.xml

http://www.freescale.com/mcds/SGTL5000XNLA3R2_IPC1752A.xml